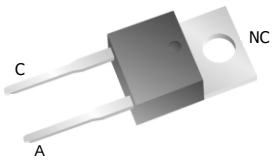
QH30TZ625
Qspeed™ Family

625 V, 30 A H-Series PFC Diode

Product Summary

$I_{F(AVG)}$	30	A
V_{RRM}	625	V
Q_{RR} (Typ at 125 °C)	180	nC
I_{RRM} (Typ at 125 °C)	5.8	A
Softness t_B/t_A (Typ at 125 °C)	0.3	

Pin Assignment



TO-220AC
QH30TZ625

A → K

RoHS Compliant
Package uses Lead-free plating and
Green mold compound.
Halogen free per IEC 61249-2-21.

General Description

This device has the lowest Q_{RR} of any 625 V silicon diode. Its recovery characteristics increases efficiency, reduces EMI and eliminates snubbers. Replaces SiC diodes for similar efficiency performance in high switching frequency applications.

Applications

- Power Factor Correction boost diode
- Server power supplies
- Motor drive circuits
- DC-AC inverters
- Output rectifier

Features

-
- High dI_F/dt capable (1000 A / µs)
- Soft recovery

Benefits

- Increases efficiency
  - Eliminates need for snubber circuits
  - Reduces EMI filter component size & count
- Enables extremely fast switching

Absolute Maximum Ratings

Absolute maximum ratings are the values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Symbol	Parameter	Conditions	Rating	Units
V_{RRM}	Peak repetitive reverse voltage	T_J = 25 °C	625	V
$I_{F(AVG)}$	Average forward current	T_J = 150 °C, T_C = 25 °C	30	A
I_{FSM}	Non-repetitive peak surge current	60 Hz, ½ cycle, T_C = 25 °C	160	A
I_{FSM}	Non-repetitive peak surge current	½ cycle of t = 28 µs Sinusoid, T_C = 25 °C	350	A
T_J	Operating junction temperature range		-55 to 150	°C
T_{STG}	Storage temperature		-55 to 150	°C
	Lead soldering temperature	Leads at 1.6 mm from case, 10 sec	300	°C
V_{ISOL}	Isolation voltage (leads-to-tab)	AC, TO-220	2500	V
P_D	Power dissipation	T_C = 25 °C	78	W

Thermal Resistance

Symbol	Resistance from:	Conditions	Rating	Units
$R_{\theta JA}$	Junction to ambient	TO-220	62	°C/W
$R_{\theta JC}$	Junction to case		1.6	°C/W

Electrical Specifications at T_J= 25 °C (unless otherwise specified)

Symbol	Parameter	Conditions		Min	Typ	Max	Units
DC Characteristics							
I_R	Reverse current	V_R = 625 V, T_J = 25 °C		-	-	500	µA
		V_R = 625 V, T_J = 125 °C		-	3.7	-	mA
V_F	Forward voltage	I_F = 30 A, T_J = 25 °C		-	2.75	3.15	V
		I_F = 30 A, T_J = 150 °C		-	2.32	-	V
C_J	Junction capacitance	V_R = 10 V, 1 MHz		-	142	-	pF
Dynamic Characteristics							
t_{RR}	Reverse recovery time	di/dt = 200 A/µs V_R = 400 V, I_F = 30 A	T_J = 25 °C	-	28.4	-	ns
			T_J = 125 °C	-	47.0	-	ns
Q_{RR}	Reverse recovery charge	di/dt = 200 A/µs V_R = 400 V, I_F = 30 A	T_J = 25 °C	-	65	105	nC
			T_J = 125 °C	-	180	-	nC
I_{RRM}	Maximum reverse recovery current	di/dt = 200 A/µs V_R = 400 V, I_F = 30 A	T_J = 25 °C	-	3.5	5.0	A
			T_J = 125 °C	-	5.8	-	A
S	Softness factor = $\frac{t_B}{t_A}$	di/dt = 200 A/µs V_R = 400 V, I_F = 30 A	T_J = 25 °C	-	0.5	-	
			T_J = 125 °C	-	0.3	-	

Note to component engineers: H-Series diodes employ Schottky technologies in their design and construction. Therefore, Component Engineers should plan their test setups to be similar to those for traditional Schottky test setups. (For additional details, see Application Note AN-300.)

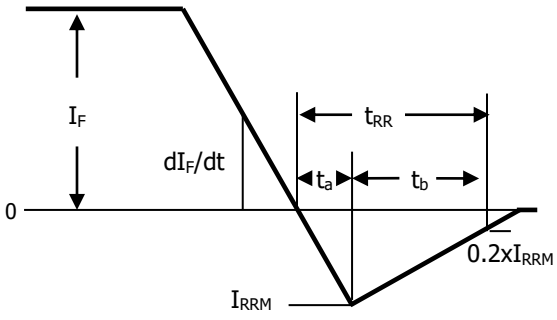


Figure 1. Reverse Recovery Definitions

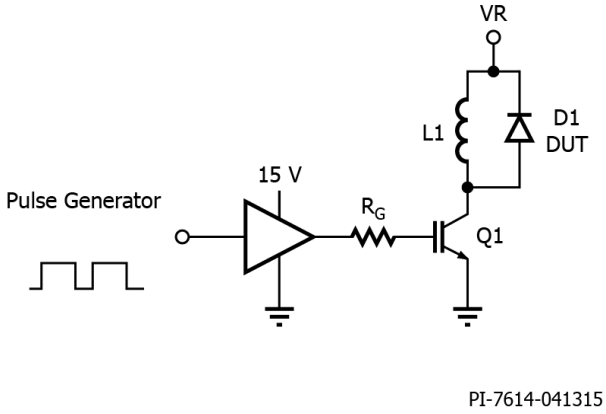


Figure 2. Reverse Recovery Test Circuit

Electrical Specifications at T_J = 25 °C (unless otherwise specified)

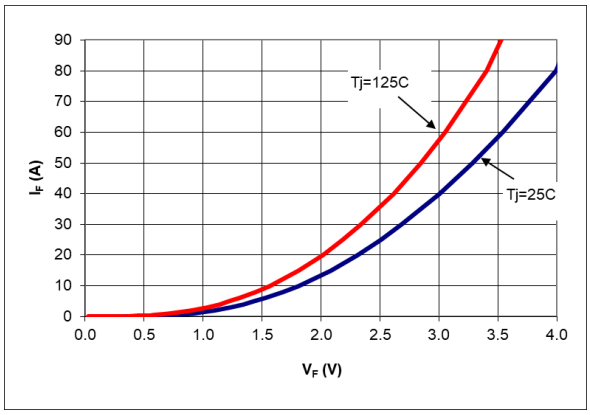


Figure 3. Typical I_F vs V_F

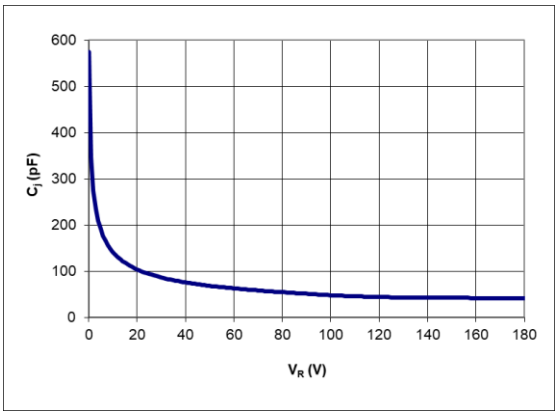


Figure 4. Typical C_j vs V_R

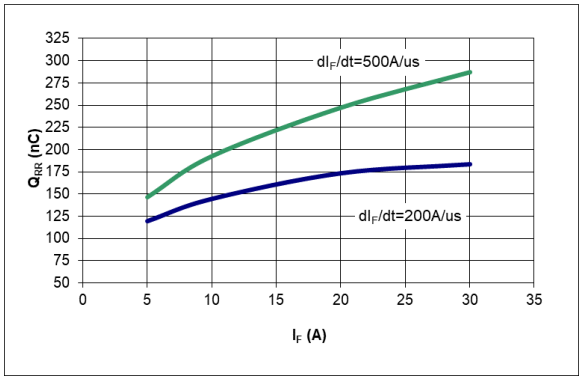


Figure 5. Typical Q_{RR} vs I_F at T_J = 125 °C

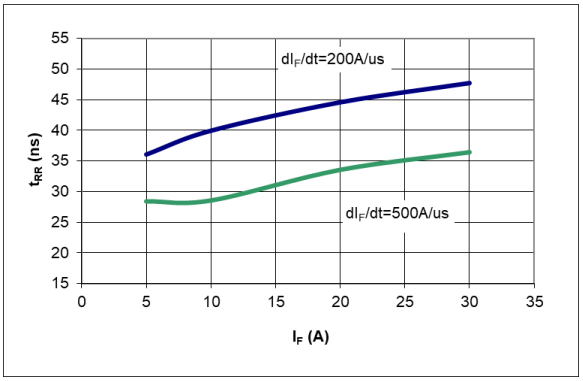


Figure 6. Typical t_{RR} vs I_F at T_J = 125 °C

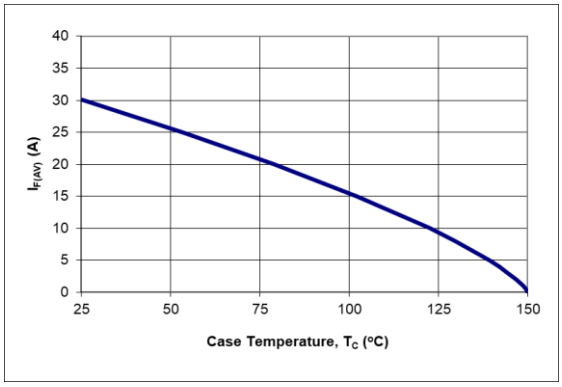


Figure 7. DC Current Derating Curve

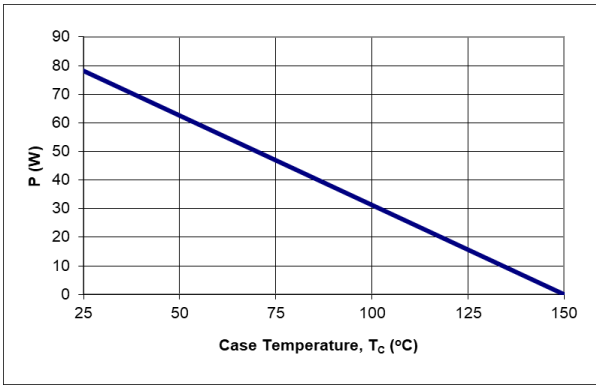


Figure 8. Power Derating Curve

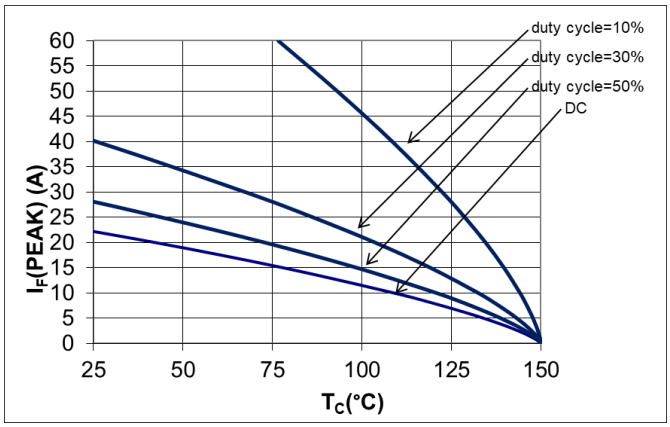


Figure 9. I_F(PEAK) vs T_C, f = 70 kHz

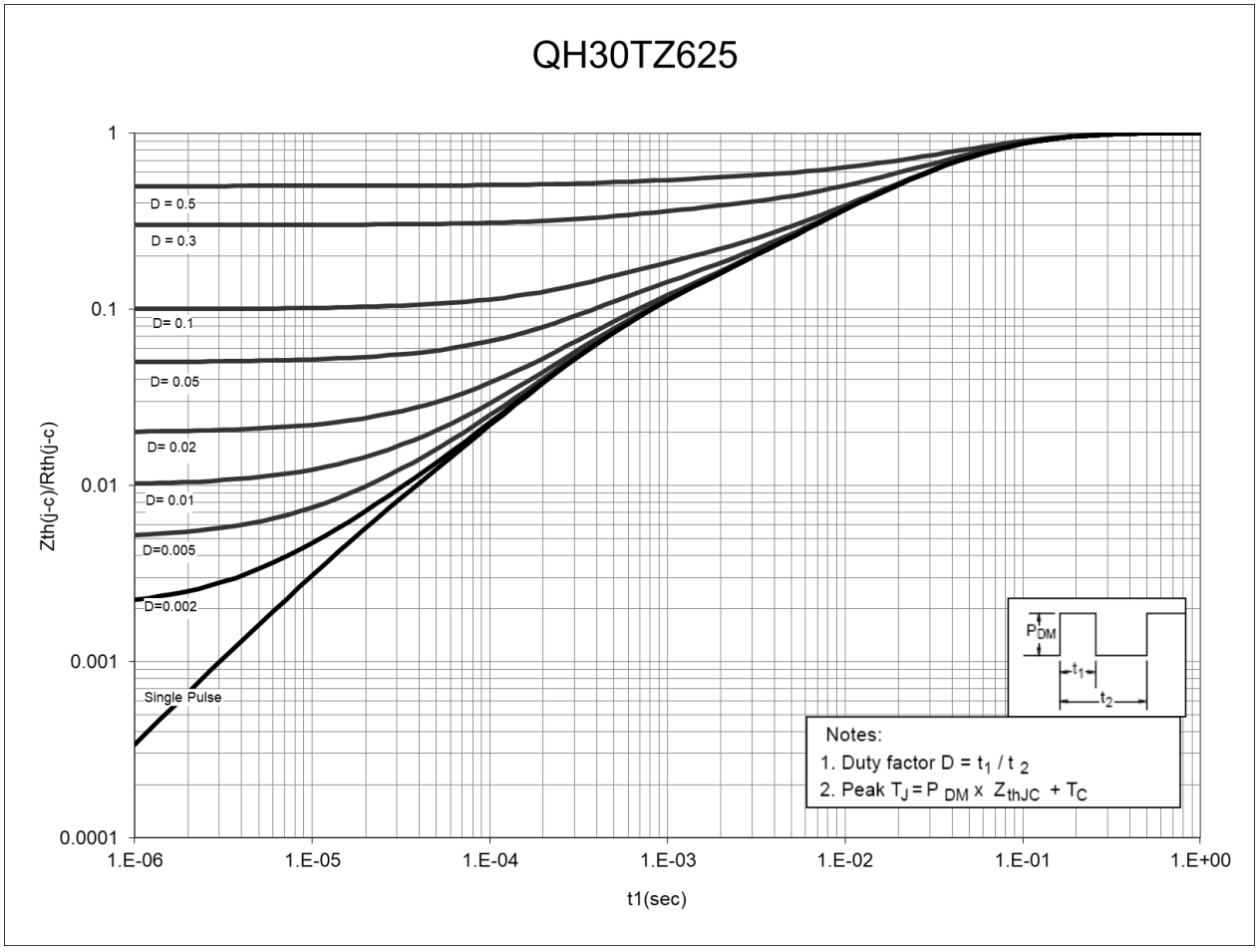
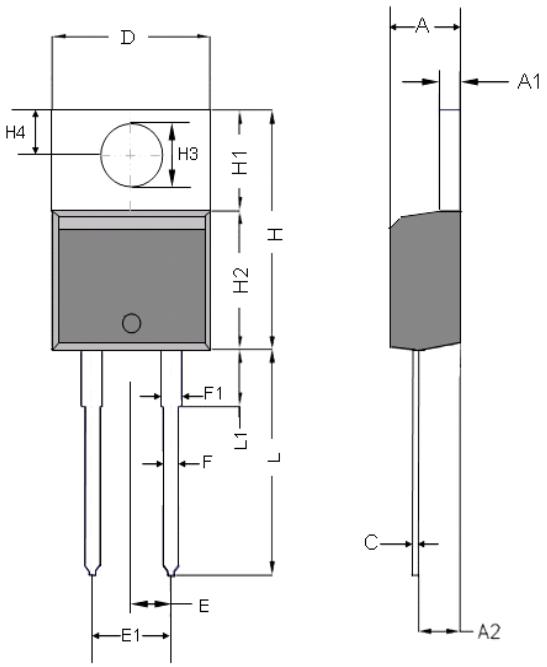


Figure 10. Normalized Maximum Transient Thermal Impedance

Dimensional Outline Drawings

TO-220AC



	Millimeters	
Dim	**MIN**	**MAX**
A	4.32	4.70
A1	1.14	1.40
A2	2.03	2.79
C	0.34	0.610
D	9.65	10.67
E	2.49	2.59
E1	4.98	5.18
F	0.508	1.016
F1	1.14	1.78
H	14.71	16.51
H1	5.84	6.795
H2	8.40	9.00
H3	3.53	3.96
H4	2.54	3.05
L	12.70	14.22
L1	-	6.35

Mechanical Mounting Method	Maximum Torque / Pressure specification
Screw through hole in package tab	1 Newton Meter (nm) or 8.8 inch-pounds (lb-in)
Clamp against package body	12.3 kilogram-force per square centimeter (kgf/cm^2) or 175 lbf/in^2

Soldering time and temperature: This product has been designed for use with high-temperature, lead-free solder. The component leads can be subjected to a maximum temperature of 300 °C, for up to 10 seconds. See Application Note AN-303, for more details.

Ordering Information

Part Number	Package	Packing
QH30TZ625	TO-220AC	50 units/tube

The information contained in this document is subject to change without notice.

Revision	Notes	Date
1.0	Preliminary release.	05/22
1.1	Production release.	12/22

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Power Integrations Worldwide Sales Support Locations

WORLD HEADQUARTERS
5245 Hellyer Avenue
San Jose, CA 95138, USA.
Main: +1-408-414-9200
Customer Service:
Worldwide: +1-65-635-64480
Americas: +1-408-414-9621
e-mail: usasales@power.com

CHINA (SHANGHAI)
Rm 2410, Charity Plaza, No. 88,
North Caoxi Road,
Shanghai, PRC 200030
Phone: +86-21-6354-6323
e-mail: chinasales@power.com

CHINA (SHENZHEN)
17/F, Hivac Building, No. 2, Keji Nan 8th Road, Nanshan District,
Shenzhen, China, 518057
Phone: +86-755-8672-8689
e-mail: chinasales@power.com

GERMANY
(AC-DC/LED/Motor Control Sales)
Einsteinring 24
85609 Dornach/Aschheim
Germany
Tel: +49-89-5527-39100
e-mail: eurosales@power.com

GERMANY (Gate Driver Sales)
HellwegForum 3
59469 Ense
Germany
Tel: +49-2938-64-39990
e-mail: igbt-driver.sales@power.com

INDIA
#1, 14th Main Road
Vasanthanagar
Bangalore-560052
India
Phone: +91-80-4113-8020
e-mail: indiasales@power.com

ITALY
Via Milanese 20, 3rd. Fl.
20099 Sesto San Giovanni (MI) Italy
Phone: +39-024-550-8701
e-mail: eurosales@power.com

JAPAN
Yusen Shin-Yokohama 1-chome Bldg.
1-7-9, Shin-Yokohama, Kohoku-ku
Yokohama-shi,
Kanagawa 222-0033 Japan
Phone: +81-45-471-1021
e-mail: japansales@power.com

KOREA
RM 602, 6FL
Korea City Air Terminal B/D,
159-6
Samsung-Dong, Kangnam-Gu,
Seoul, 135-728 Korea
Phone: +82-2-2016-6610
e-mail: koreasales@power.com

SINGAPORE
51 Newton Road,
#19-01/05 Goldhill Plaza
Singapore, 308900
Phone: +65-6358-2160
e-mail: singaporesales@power.com

TAIWAN
5F, No. 318, Nei Hu Rd.,
Sec. 1
Nei Hu District
Taipei 11493, Taiwan R.O.C.
Phone: +886-2-2659-4570
e-mail: taiwansales@power.com

UK
Building 5, Suite 21
The Westbrook Centre
Milton Road
Cambridge
CB4 1YG
Phone: +44 (0) 7823-557484
e-mail: eurosales@power.com

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